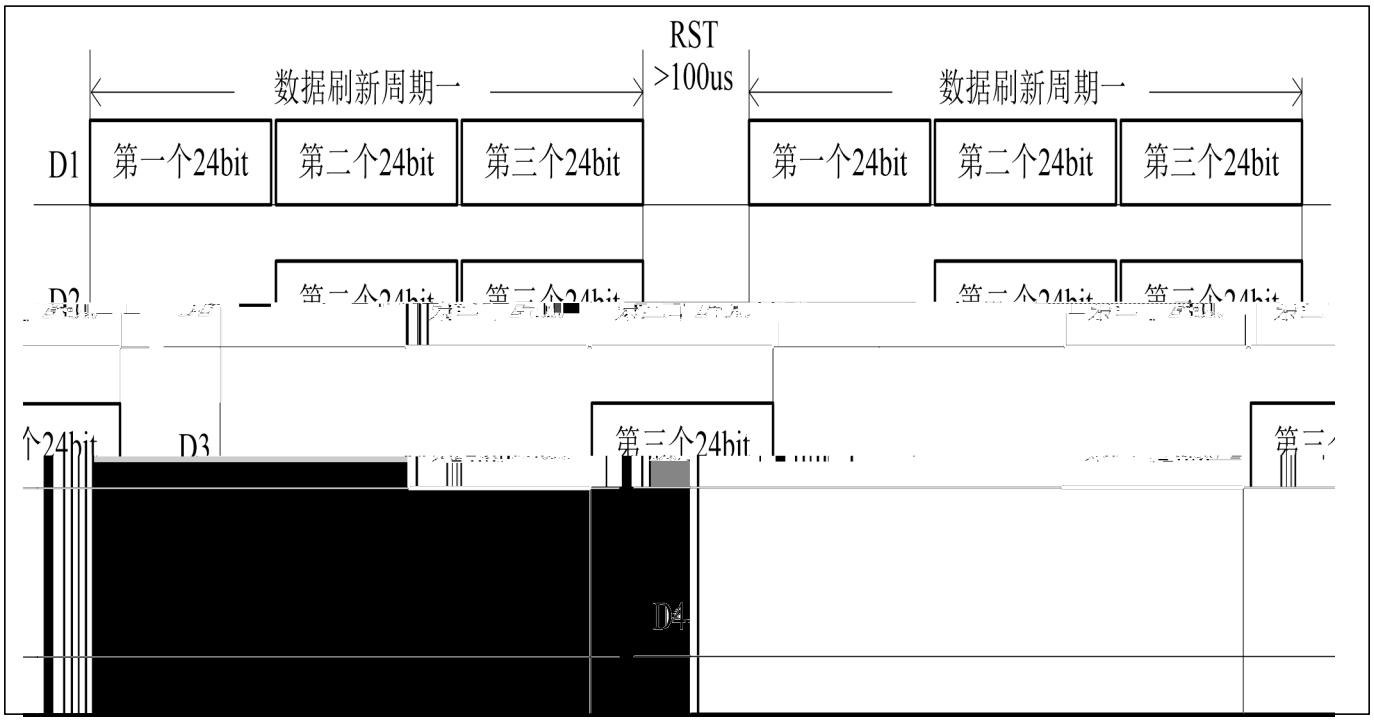
Part [redacted]

OUT/RGB [redacted] Output PWM [redacted]	Fpwm	-	4.5	-	KHz	Iout=5mA	OUT 200Ω VDD
4 Signal transmission delay	t_{PLH}	-	80	-	ns	DOUT 30pF,DIN	DOUT
	t_{PHL}	-	80	-	ns		

DOUT (5
Conversion tir

[redacted]

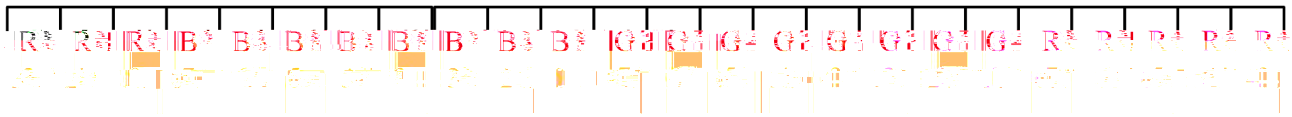
Date transmission mode



D1 MCU D2 D3 D4

Note: D1 refers to the data sent by MCU, and D2, D3 and D4 refer to the data automatically shaped and forwarded by cascade circuit

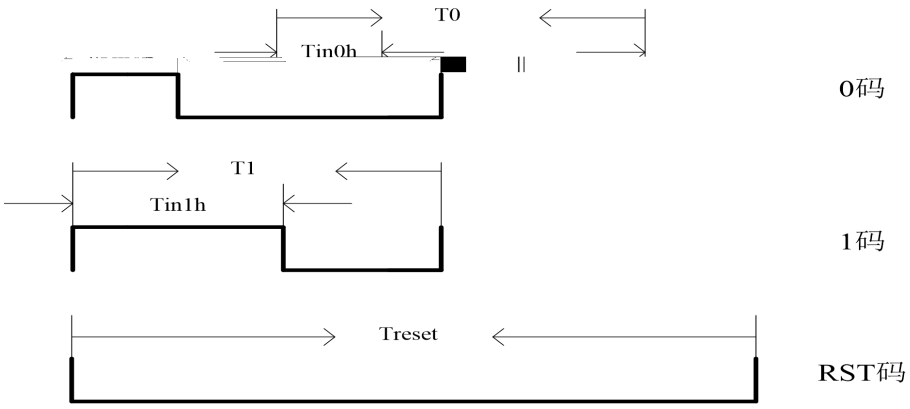
24bit 24bit data structure



GRB

Note: high order first send, send data in the order of GrB

:Time sequence waveform:



[redacted]

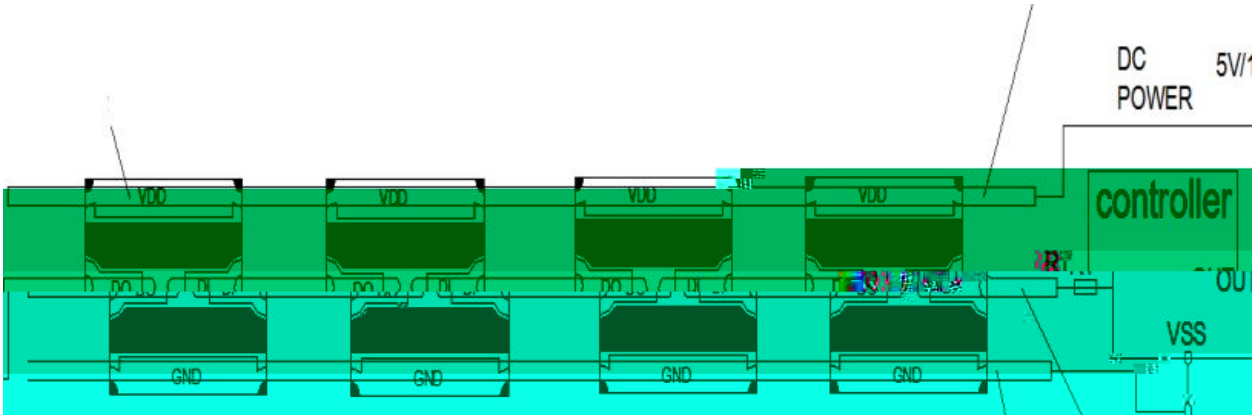
0 Input 0 code high level time	T0h	0.3	-		us
1 Input 1 code high level time	T1h	0.9	-	-	us
0 Input 0 code low level time	T0L	0.9	-	-	us
1 Input 1 code low level time	T1L	0.3	-	-	us
0 /1 0 code /1 code cycle	T0/T1	1.2	-	-	us
RESET Reset code low level time	reset	200	-	-	us

1.2us 0 1 0 1

20us

Note: When writing the program, the minimum requirement for the original code cycle is 1.2us. The high-level time of code 0 and code 1 should be within the range specified in the table above. The low-level time of code 0 and code 1 should be less than 20us

redcl **Application circuit diagram:**



ä

XING LIGHT

Part

焊接指

Guideline for Solder

使用烙铁人手焊接

30W

300 3

LED

Manual welding is recommended only for repair and heavy industry situations. A soldering iron of less than 30W is recommended to be used ito

焊接指导（2）

Guideline for Soldering (2)

清洗：

30 3 50

30

LED

300W LED

LED

It is recommended that alcohol be used as a solvent for cleaning after soldering. Cleaning is to go under 30 for 3 minutes or 50 for 30 seconds. When using other solvents, it should be confirmed beforehand whether the solvents will dissolve the package and the resin or not.

Ultrasonic cleaning is also an effective way for cleaning. But the influence of Ultrasonic cleaning on LED depends on factors such as ultrasonic power. Generally, the ultrasonic power should not be higher than 300W. Before cleaning, a pretest should be done to confirm whether any damage to LEDs will occur.

* **注意：** PCB

PCB

* This general guideline may not apply to all PCB designs and configurations of all soldering equipment. The technics in practise is influenced by many factors, it should be specialized base on the PCB designs and configurations of the soldering equipment..